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Kind regards,

Team Nexperia

# 74HC4067; 74HCT4067

# 16-channel analog multiplexer/demultiplexer Rev. 6 — 22 May 2015

**Product data sheet** 

#### 1. **General description**

The 74HC4067; 74HCT4067 is a single-pole 16-throw analog switch (SP16T) suitable for use in analog or digital 16:1 multiplexer/demultiplexer applications. The switch features four digital select inputs (S0, S1, S2 and S3), sixteen independent inputs/outputs (Yn), a common input/output (Z) and a digital enable input (E). When E is HIGH, the switches are turned off. Inputs include clamp diodes. This enables the use of current limiting resistors to interface inputs to voltages in excess of V<sub>CC</sub>.

#### 2. Features and benefits

- Input levels S0, S1, S2, S3 and E inputs:
  - ◆ For 74HC4067: CMOS level
  - ◆ For 74HCT4067: TTL level
- Low ON resistance:
  - 80  $\Omega$  (typical) at  $V_{CC} = 4.5 \text{ V}$
  - 70  $\Omega$  (typical) at  $V_{CC} = 6.0 \text{ V}$
  - 60  $\Omega$  (typical) at  $V_{CC} = 9.0 \text{ V}$
- Specified in compliance with JEDEC standard no. 7A
- ESD protection:
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - MM JESD22-A115-A exceeds 200 V
  - CDM JESD22-C101E exceeds 1000 V
- Multiple package options
- Specified from -40 °C to +85 °C and -40 °C to +125 °C
- Typical 'break before make' built-in

#### **Applications** 3.

- Analog multiplexing and demultiplexing
- Digital multiplexing and demultiplexing
- Signal gating

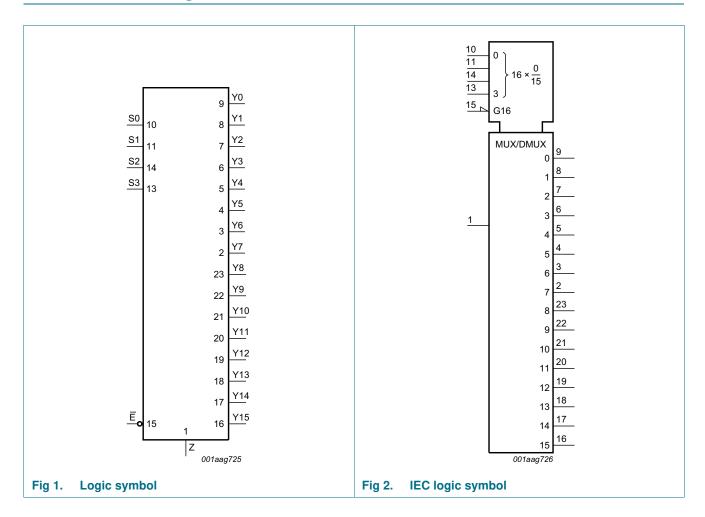


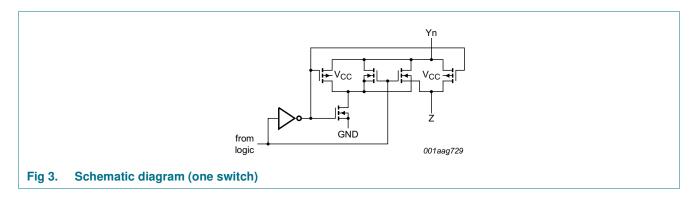
### 4. Ordering information

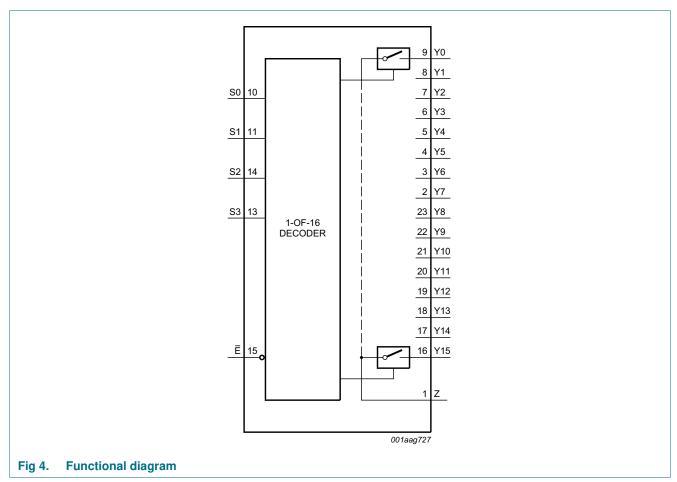
Table 1. Ordering information

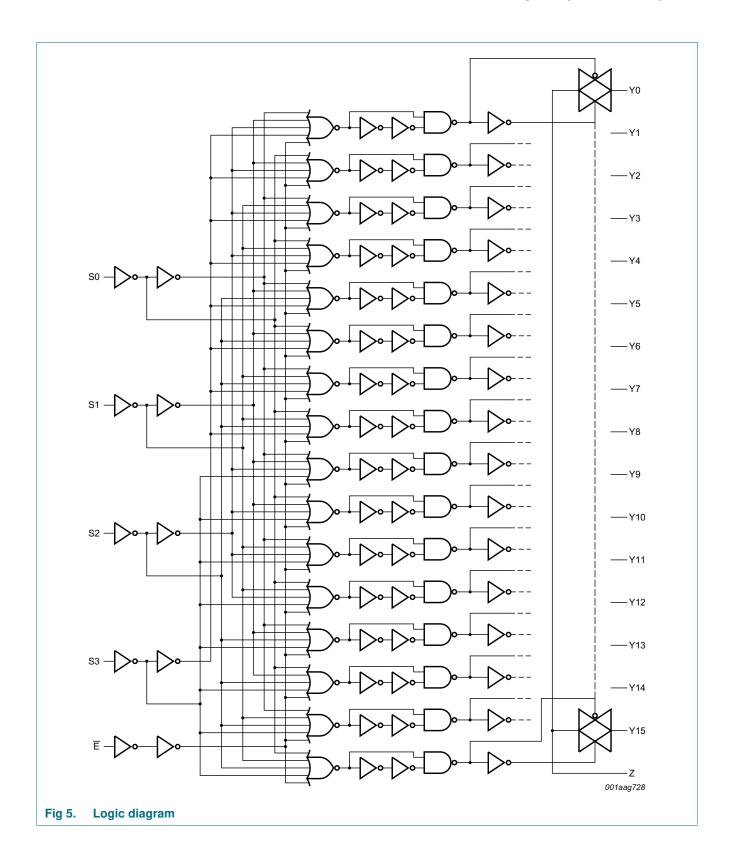
Type number	Package			
	Temperature range	Name	Description	Version
74HC4067D	-40 °C to +125 °C	SO24	plastic small outline package; 24 leads;	SOT137-1
74HCT4067D			body width 7.5 mm	
74HC4067DB	-40 °C to +125 °C	SSOP24	plastic shrink small outline package; 24 leads;	SOT340-1
74HCT4067DB			body width 5.3 mm	
74HC4067PW	-40 °C to +125 °C	TSSOP24	plastic thin shrink small outline package; 24 leads;	SOT355-1
74HCT4067PW			body width 4.4 mm	
74HC4067BQ	-40 °C to +125 °C	DHVQFN24	plastic dual in-line compatible thermal enhanced very	SOT815-1
74HCT4067BQ			thin quad flat package; no leads; 24 terminals; body $3.5 \times 5.5 \times 0.85$ mm	

### 5. Functional diagram



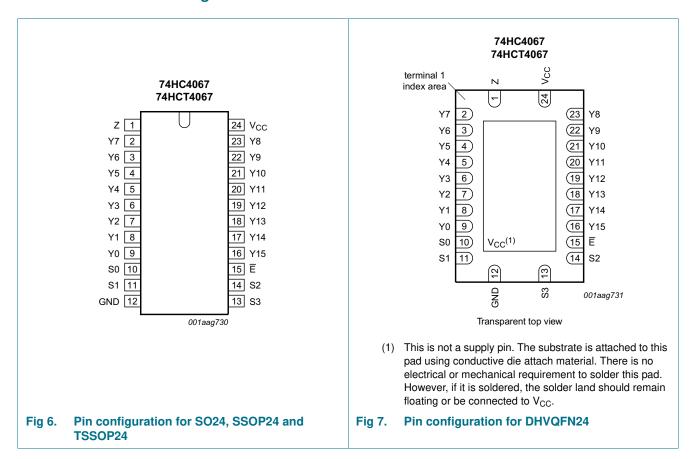






### 6. Pinning information

#### 6.1 Pinning



#### 6.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
Z	1	common input or output
Y7, Y6, Y5, Y4, Y3, Y2, Y1, Y0, Y15, Y14, Y13, Y12, Y11, Y10, Y9, Y8	2, 3, 4, 5, 6, 7, 8, 9, 16, 17, 18, 19, 20, 21, 22, 23	independent input or output
S0, S1, S3, S2	10, 11, 13, 14	address input 0
GND	12	ground (0 V)
Ē	15	enable input (active LOW)
V <sub>CC</sub>	24	supply voltage

### 7. Functional description

Table 3. Function table[1]

Inputs					Channel ON
E	S3	S2	S1	S0	
L	L	L	L	L	Y0 to Z
L	L	L	L	Н	Y1 to Z
L	L	L	Н	L	Y2 to Z
L	L	L	Н	Н	Y3 to Z
L	L	Н	L	L	Y4 to Z
L	L	Н	L	Н	Y5 to Z
L	L	Н	Н	L	Y6 to Z
L	L	Н	Н	Н	Y7 to Z
L	Н	L	L	L	Y8 to Z
L	Н	L	L	Н	Y9 to Z
L	Н	L	Н	L	Y10 to Z
L	Н	L	Н	Н	Y11 to Z
L	Н	Н	L	L	Y12 to Z
L	Н	Н	L	Н	Y13 to Z
L	Н	Н	Н	L	Y14 to Z
L	Н	Н	Н	Н	Y15 to Z
Н	X	X	X	X	-

<sup>[1]</sup> H = HIGH voltage level;

### 8. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		Min	Max	Unit
V <sub>CC</sub>	supply voltage	]	1]	-0.5	+11.0	V
I <sub>IK</sub>	input clamping current	$V_{I} < -0.5 \text{ V or } V_{I} > V_{CC} + 0.5 \text{ V}$		-	±20	mA
I <sub>SK</sub>	switch clamping current	$V_{SW} < -0.5 \text{ V or } V_{SW} > V_{CC} + 0.5 \text{ V}$		-	±20	mA
I <sub>SW</sub>	switch current	$V_{SW} = -0.5 \text{ V to } V_{CC} + 0.5 \text{ V}$		-	±25	mA
I <sub>CC</sub>	supply current			-	+50	mA
I <sub>GND</sub>	ground current			-50	-	mA
T <sub>stg</sub>	storage temperature			-65	+150	°C

L = LOW voltage level;

X = don't care.

 Table 4.
 Limiting values ...continued

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
P <sub>tot</sub>	total power dissipation	$T_{amb} = -40  ^{\circ}\text{C} \text{ to } +125  ^{\circ}\text{C}$			
		SO24 package [2]	-	500	mW
		SSOP24 package [3]	-	500	mW
		TSSOP24 package [3]	-	500	mW
		DHVQFN24 package [4]	-	500	mW
Р	power dissipation	per switch	-	100	mW

<sup>[1]</sup> To avoid drawing V<sub>CC</sub> current out of terminal Z, when switch current flows in terminals Yn, the voltage drop across the bidirectional switch must not exceed 0.4 V. If the switch current flows into terminal Z, no V<sub>CC</sub> current will flow out of terminals Yn. In this case there is no limit for the voltage drop across the switch, but the voltages at Yn and Z may not exceed V<sub>CC</sub> or GND.

- [2] For SO24 package:  $P_{tot}$  derates linearly with 8 mW/K above 70 °C.
- [3] For SSOP24 and TSSOP24 packages: Ptot derates linearly with 5.5 mW/K above 60 °C.
- [4] For DHVQFN24 package: Ptot derates linearly with 4.5 mW/K above 60 °C.

### 9. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
74HC406	7					
$V_{CC}$	supply voltage		2.0	5.0	10.0	V
VI	input voltage		GND	-	V <sub>CC</sub>	V
$V_{SW}$	switch voltage		GND	-	V <sub>CC</sub>	V
Δt/ΔV	input transition rise and fall rate	V <sub>CC</sub> = 2.0 V	-	-	625	ns
		V <sub>CC</sub> = 4.5 V	-	1.67	139	ns
		$V_{CC} = 6.0 \text{ V}$	-	-	83	ns
		V <sub>CC</sub> = 10.0 V	-	-	31	ns
T <sub>amb</sub>	ambient temperature		-40	+25	+125	°C
74HCT40	67					
V <sub>CC</sub>	supply voltage		4.5	5.0	5.5	V
VI	input voltage		GND	-	V <sub>CC</sub>	V
$V_{SW}$	switch voltage		GND	-	V <sub>CC</sub>	V
Δt/ΔV	input transition rise and fall rate	V <sub>CC</sub> = 4.5 V	-	1.67	139	ns
T <sub>amb</sub>	ambient temperature		-40	+25	+125	°C

#### 10. Static characteristics

#### R<sub>ON</sub> resistance per switch for types 74HC4067 and 74HCT4067 Table 6.

 $V_I = V_{IH}$  or  $V_{IL}$ ; for test circuit see <u>Figure 8</u>.

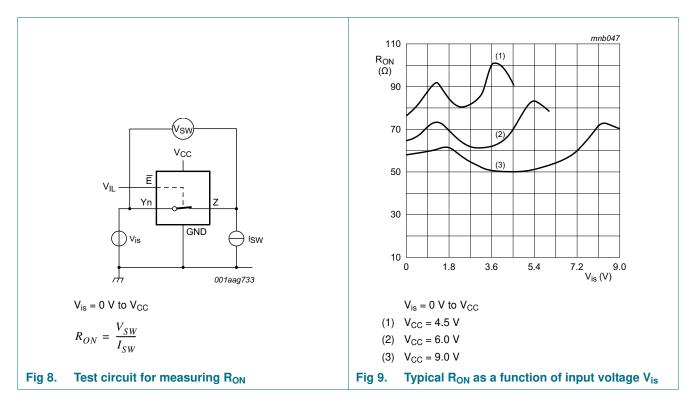
 $V_{is}$  is the input voltage at a Yn or  $\overline{Z}$  terminal, whichever is assigned as an input.

 $V_{os}$  is the output voltage at a Yn or Z terminal, whichever is assigned as an output.

For 74HC4067:  $V_{CC}$  – GND = 2.0 V, 4.5 V, 6.0 V and 9.0 V. For 74HCT4067:  $V_{CC}$  – GND = 4.5 V.

Symbol	Parameter	Conditions		25	°C	-40 °C to +125 °C ℓ		Unit
				Тур Мах		Max (85 °C)	Max (125 °C)	-
R <sub>ON(peak)</sub>	ON resistance (peak)	$V_{is} = V_{CC}$ to GND						
		$V_{CC} = 2.0 \text{ V}; I_{SW} = 100 \mu\text{A}$	<u>[1]</u>	-	-	-	-	Ω
		$V_{CC} = 4.5 \text{ V}; I_{SW} = 1000 \mu\text{A}$		110	180	225	270	Ω
		$V_{CC} = 6.0 \text{ V}; I_{SW} = 1000 \mu\text{A}$		95	160	200	240	Ω
		$V_{CC} = 9.0 \text{ V}; I_{SW} = 1000 \mu\text{A}$		75	130	165	195	Ω
R <sub>ON(rail)</sub>	ON resistance (rail)	$V_{is} = GND \text{ or } V_{CC}$						
		$V_{CC} = 2.0 \text{ V}; I_{SW} = 100 \mu\text{A}$	<u>[1]</u>	150	-	-	-	
		$V_{CC} = 4.5 \text{ V}; I_{SW} = 1000 \mu\text{A}$		90	160	200	240	Ω
		$V_{CC} = 6.0 \text{ V}; I_{SW} = 1000 \mu\text{A}$		80	140	175	210	Ω
		$V_{CC} = 9.0 \text{ V}; I_{SW} = 1000 \mu\text{A}$		70	120	150	180	Ω
$\Delta R_{ON}$	ON resistance mismatch	V <sub>is</sub> = V <sub>CC</sub> to GND						
	between channels	V <sub>CC</sub> = 2.0 V	<u>[1]</u>	-	-	-	-	Ω
		V <sub>CC</sub> = 4.5 V		9	-	-	-	Ω
		V <sub>CC</sub> = 6.0 V		8	-	-	-	Ω
		V <sub>CC</sub> = 9.0 V		6	-	-	-	Ω

<sup>[1]</sup> At supply voltages (V<sub>CC</sub> - GND) approaching 2 V, the analog switch ON resistance becomes extremely non-linear. Therefore it is recommended that these devices be used to transmit digital signals only, when using these supply voltages.



#### Table 7. Static characteristics 74HC4067

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).  $V_{is}$  is the input voltage at a Yn or Z terminal, whichever is assigned as an input.  $V_{os}$  is the output voltage at a Yn or Z terminal, whichever is assigned as an output.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
T <sub>amb</sub> = 25	°C		•			
$V_{IH}$	HIGH-level input voltage	V <sub>CC</sub> = 2.0 V	1.5	1.2	-	V
		$V_{CC} = 4.5 \text{ V}$	3.15	2.4	-	V
		$V_{CC} = 6.0 \text{ V}$	4.2	3.2	-	V
		$V_{CC} = 9.0 \text{ V}$	6.3	4.7	-	V
$V_{IL}$	LOW-level input voltage	V <sub>CC</sub> = 2.0 V	-	0.8	0.5	V
		$V_{CC} = 4.5 \text{ V}$	-	2.1	1.35	V
		$V_{CC} = 6.0 \text{ V}$	-	2.8	1.80	V
		$V_{CC} = 9.0 \text{ V}$	-	4.3	2.70	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND				
		V <sub>CC</sub> = 6.0 V	-	-	±0.1	μΑ
		V <sub>CC</sub> = 10.0 V	-	-	±0.2	μΑ
I <sub>S(OFF)</sub>	OFF-state leakage current	$V_{CC} = 10.0 \text{ V}; V_I = V_{IH} \text{ or } V_{IL};$ $ V_{SW}  = V_{CC} - \text{GND}; \text{ see } \frac{\text{Figure 10}}{\text{Figure 10}}$				
		per channel	-	-	±0.1	μΑ
		all channels	-	-	±0.8	μΑ
I <sub>S(ON)</sub>	ON-state leakage current	$V_{CC}$ = 10.0 V; $V_{I}$ = $V_{IH}$ or $V_{IL}$ ; $ V_{SW} $ = $V_{CC}$ – GND; see <u>Figure 11</u>	-	-	±0.8	μΑ

Table 7. Static characteristics 74HC4067 ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).  $V_{is}$  is the input voltage at a Yn or Z terminal, whichever is assigned as an input.

 $V_{os}$  is the output voltage at a Yn or Z terminal, whichever is assigned as an output.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
I <sub>CC</sub>	supply current	$V_{I} = V_{CC}$ or GND; $V_{is} = GND$ or $V_{CC}$ ; $V_{os} = V_{CC}$ or GND				
		V <sub>CC</sub> = 6.0 V	-	-	8.0	μΑ
		V <sub>CC</sub> = 10.0 V	-	-	16.0	μΑ
Cı	input capacitance		-	3.5	-	pF
T <sub>amb</sub> = -4	0 °C to +85 °C		,			
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 2.0 V	1.5	-	-	V
		$V_{CC} = 4.5 \text{ V}$	3.15	-	-	V
		$V_{CC} = 6.0 \text{ V}$	4.2	-	-	٧
		V <sub>CC</sub> = 9.0 V	6.3	-	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 2.0 V	-	-	0.50	V
		$V_{CC} = 4.5 \text{ V}$	-	-	1.35	V
		$V_{CC} = 6.0 \text{ V}$	-	-	1.80	V
		V <sub>CC</sub> = 9.0 V	-	-	2.70	V
l <sub>l</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND				
		V <sub>CC</sub> = 6.0 V	-	-	±1.0	μΑ
		V <sub>CC</sub> = 10.0 V	-	-	±2.0	μΑ
I <sub>S(OFF)</sub>	OFF-state leakage current	$V_{CC} = 10.0 \text{ V}; V_I = V_{IH} \text{ or } V_{IL};$ $ V_{SW}  = V_{CC} - \text{GND}; \text{ see } \frac{\text{Figure } 10}{\text{Figure } 10}$				
		per channel	-	-	±1.0	μΑ
		all channels	-	-	±8.0	μΑ
I <sub>S(ON)</sub>	ON-state leakage current	$V_{CC} = 10.0 \text{ V}; V_I = V_{IH} \text{ or } V_{IL};$ $ V_{SW}  = V_{CC} - \text{GND}; \text{ see } \frac{\text{Figure } 11}{\text{Figure } 11}$	-	-	±8.0	μА
I <sub>CC</sub>	supply current	$V_{I} = V_{CC}$ or GND; $V_{is} = GND$ or $V_{CC}$ ; $V_{os} = V_{CC}$ or GND				
		V <sub>CC</sub> = 6.0 V	-	-	80.0	μΑ
		V <sub>CC</sub> = 10.0 V	-	-	160	μΑ
T <sub>amb</sub> = -4	0 °C to +125 °C	,				
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 2.0 V	1.5	-	-	٧
		$V_{CC} = 4.5 \text{ V}$	3.15	-	-	٧
		$V_{CC} = 6.0 \text{ V}$	4.2	-	-	V
		V <sub>CC</sub> = 9.0 V	6.3	-	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 2.0 V	-	-	0.50	V
		V <sub>CC</sub> = 4.5 V	-	-	1.35	V
		V <sub>CC</sub> = 6.0 V	-	-	1.80	V
		V <sub>CC</sub> = 9.0 V	-	-	2.70	V
l <sub>l</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND				
		V <sub>CC</sub> = 6.0 V	-	-	±1.0	μΑ
		V <sub>CC</sub> = 10.0 V	-	-	±2.0	μΑ

#### Table 7. Static characteristics 74HC4067 ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).  $V_{is}$  is the input voltage at a Yn or Z terminal, whichever is assigned as an input.  $V_{os}$  is the output voltage at a Yn or Z terminal, whichever is assigned as an output.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
I <sub>S(OFF)</sub>	OFF-state leakage current	$V_{CC}$ = 10.0 V; $V_{I}$ = $V_{IH}$ or $V_{IL}$ ; $ V_{SW} $ = $V_{CC}$ - GND; see Figure 10				
		per channel	-	-	±1.0	μΑ
		all channels	-	-	±8.0	μΑ
I <sub>S(ON)</sub>	ON-state leakage current	$V_{CC}$ = 10.0 V; $V_{I}$ = $V_{IH}$ or $V_{IL}$ ; $ V_{SW} $ = $V_{CC}$ – GND; see Figure 11	-	-	±8.0	μΑ
I <sub>CC</sub>	supply current	$V_I = V_{CC}$ or GND; $V_{is} = GND$ or $V_{CC}$ ; $V_{os} = V_{CC}$ or GND				
		V <sub>CC</sub> = 6.0 V	-	-	160	μΑ
		V <sub>CC</sub> = 10.0 V	-	-	320	μΑ

#### Table 8. Static characteristics 74HCT4067

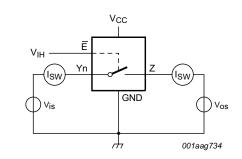
At recommended operating conditions; voltages are referenced to GND (ground = 0 V).  $V_{is}$  is the input voltage at a Yn or Z terminal, whichever is assigned as an input.  $V_{os}$  is the output voltage at a Yn or Z terminal, whichever is assigned as an output.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
T <sub>amb</sub> = 25	°C					'
$V_{IH}$	HIGH-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	2.0	1.6	-	V
$V_{IL}$	LOW-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	-	1.2	0.8	V
II	input leakage current	$V_I = V_{CC}$ or GND; $V_{CC} = 5.5 \text{ V}$	-	-	±0.1	μΑ
I <sub>S(OFF)</sub>	OFF-state leakage current	$V_{CC}$ = 5.5 V; $V_{I}$ = $V_{IH}$ or $V_{IL}$ ; $ V_{SW} $ = $V_{CC}$ – GND; see Figure 10				
		per channel	-	-	±0.1	μΑ
		all channels	-	-	±0.8	μΑ
I <sub>S(ON)</sub>	ON-state leakage current	$V_{CC}$ = 5.5 V; $V_{I}$ = $V_{IH}$ or $V_{IL}$ ; $ V_{SW} $ = $V_{CC}$ – GND; see Figure 11	-	-	±0.8	μΑ
I <sub>CC</sub>	supply current	$V_I = V_{CC}$ or GND; $V_{is} = GND$ or $V_{CC}$ ; $V_{os} = V_{CC}$ or GND; $V_{CC} = 4.5$ V to 5.5 V	-	-	8.0	μА
Δl <sub>CC</sub>	additional supply current	per input pin; $V_I = V_{CC} - 2.1 \text{ V}$ ; other inputs at $V_{CC}$ or GND; $V_{CC} = 4.5 \text{ V}$ to 5.5 V				
		pin E	-	60	216	μΑ
		pin Sn	-	50	180	μΑ
Cı	input capacitance		-	3.5	-	pF
T <sub>amb</sub> = -4	0 °C to +85 °C		-		-	
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	2.0	-	-	٧
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	-	-	0.8	٧
I <sub>I</sub>	input leakage current	$V_I = V_{CC}$ or GND; $V_{CC} = 5.5 \text{ V}$	-	-	±1.0	μΑ
I <sub>S(OFF)</sub>	OFF-state leakage current	$V_{CC}$ = 5.5 V; $V_{I}$ = $V_{IH}$ or $V_{IL}$ ; $ V_{SW} $ = $V_{CC}$ – GND; see <u>Figure 10</u>				
		per channel	-	-	±1.0	μΑ
		all channels	-	-	±8.0	μА

#### Table 8. Static characteristics 74HCT4067 ...continued

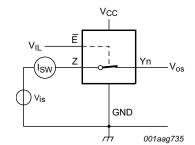
At recommended operating conditions; voltages are referenced to GND (ground = 0 V).  $V_{is}$  is the input voltage at a Yn or Z terminal, whichever is assigned as an input.  $V_{os}$  is the output voltage at a Yn or Z terminal, whichever is assigned as an output.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
I <sub>S(ON)</sub>	ON-state leakage current	$V_{CC}$ = 5.5 V; $V_I$ = $V_{IH}$ or $V_{IL}$ ; $ V_{SW} $ = $V_{CC}$ - GND; see <u>Figure 11</u>	-	-	±8.0	μА
I <sub>CC</sub>	supply current	$V_I = V_{CC}$ or GND; $V_{is} = GND$ or $V_{CC}$ ; $V_{os} = V_{CC}$ or GND; $V_{CC} = 4.5$ V to 5.5 V	-	-	80.0	μΑ
Δl <sub>CC</sub>	additional supply current	per input pin; $V_I = V_{CC} - 2.1 \text{ V}$ ; other inputs at $V_{CC}$ or GND; $V_{CC} = 4.5 \text{ V}$ to 5.5 V				
		pin E	-	-	270	μΑ
		pin Sn	-	-	225	μΑ
$T_{amb} = -4$	0 °C to +125 °C		,			
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	2.0	-	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	-	-	8.0	V
l <sub>l</sub>	input leakage current	$V_I = V_{CC}$ or GND; $V_{CC} = 5.5 \text{ V}$	-	-	±1.0	μΑ
I <sub>S(OFF)</sub>	OFF-state leakage current	$V_{CC} = 5.5 \text{ V}; V_I = V_{IH} \text{ or } V_{IL};$ $ V_{SW}  = V_{CC} - \text{GND}; \text{ see } \frac{\text{Figure 10}}{\text{Figure 10}}$				
		per channel	-	-	±1.0	μΑ
		all channels	-	-	±8.0	μΑ
I <sub>S(ON)</sub>	ON-state leakage current	$V_{CC}$ = 5.5 V; $V_{I}$ = $V_{IH}$ or $V_{IL}$ ; $ V_{SW} $ = $V_{CC}$ - GND; see <u>Figure 11</u>	-	-	±8.0	μΑ
I <sub>CC</sub>	supply current	$V_I = V_{CC}$ or GND; $V_{is} = GND$ or $V_{CC}$ ; $V_{os} = V_{CC}$ or GND; $V_{CC} = 4.5$ V to 5.5 V	-	-	160	μА
$\Delta I_{CC}$	additional supply current	per input pin; $V_1 = V_{CC} - 2.1 \text{ V}$ ; other inputs at $V_{CC}$ or GND; $V_{CC} = 4.5 \text{ V}$ to 5.5 V				
		pin E	-	-	294	μΑ
		pin Sn	-	-	245	μА



$$\begin{split} &V_{is} = V_{CC} \text{ and } V_{os} = GND \\ &V_{is} = GND \text{ and } V_{os} = V_{CC} \end{split}$$

Fig 10. Test circuit for measuring OFF-state leakage current



 $V_{is} = V_{CC}$  and  $V_{os} = open$  $V_{is} = GND$  and  $V_{os} = open$ 

Fig 11. Test circuit for measuring ON-state leakage current

### 11. Dynamic characteristics

#### Table 9. Dynamic characteristics 74HC4067

 $GND = 0 \ V; \ t_r = t_f = 6 \ ns; \ C_L = 50 \ pF \ unless \ specified \ otherwise; for test \ circuit \ see \ \underline{Figure \ 14}.$ 

*V*<sub>is</sub> is the input voltage at a Yn or *Z* terminal, whichever is assigned as an input.

 $V_{os}$  is the output voltage at a Yn or Z terminal, whichever is assigned as an output.

Symbol	Parameter	Conditions	25	°C	-40 °C to	o +125 °C	Unit
			Тур	Max	Max (85 °C)	Max (125 °C)	-
t <sub>pd</sub>	propagation delay	Yn to Z; see Figure 12 [1][2]					
		V <sub>CC</sub> = 2.0 V	25	75	95	110	ns
		V <sub>CC</sub> = 4.5 V	9	15	19	22	ns
		V <sub>CC</sub> = 6.0 V	7	13	16	19	ns
		V <sub>CC</sub> = 9.0 V	5	9	11	14	ns
		Z to Yn					
		V <sub>CC</sub> = 2.0 V	18	60	75	90	ns
		V <sub>CC</sub> = 4.5 V	6	12	15	18	ns
		V <sub>CC</sub> = 6.0 V	5	10	13	15	ns
		V <sub>CC</sub> = 9.0 V	4	8	10	12	ns
t <sub>off</sub>	turn-off time	E to Yn; see Figure 13					
		V <sub>CC</sub> = 2.0 V	74	250	315	375	ns
		V <sub>CC</sub> = 4.5 V	27	50	63	75	ns
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF	27	-	-	-	ns
		V <sub>CC</sub> = 6.0 V	22	43	54	64	ns
		V <sub>CC</sub> = 9.0 V	20	38	48	57	ns
		Sn to Yn					
		V <sub>CC</sub> = 2.0 V	83	250	315	375	ns
		V <sub>CC</sub> = 4.5 V	30	50	63	75	ns
		$V_{CC} = 5.0 \text{ V}; C_L = 15 \text{ pF}$	29	-	-	-	ns
		$V_{CC} = 6.0 \text{ V}$	24	43	54	64	ns
		V <sub>CC</sub> = 9.0 V	21	38	48	57	ns
		E to Z					
		$V_{CC} = 2.0 \text{ V}$	85	275	345	415	ns
		V <sub>CC</sub> = 4.5 V	31	55	69	83	ns
		$V_{CC} = 6.0 \text{ V}$	25	47	59	71	ns
		V <sub>CC</sub> = 9.0 V	24	42	53	63	ns
		Sn to Z					
		V <sub>CC</sub> = 2.0 V	94	290	365	435	ns
		V <sub>CC</sub> = 4.5 V	34	58	73	87	ns
		V <sub>CC</sub> = 6.0 V	27	47	62	74	ns
		V <sub>CC</sub> = 9.0 V	25	45	56	68	ns

 Table 9.
 Dynamic characteristics 74HC4067 ...continued

GND = 0 V;  $t_r = t_f = 6$  ns;  $C_L = 50$  pF unless specified otherwise; for test circuit see Figure 14.

 $V_{is}$  is the input voltage at a Yn or Z terminal, whichever is assigned as an input.

Vos is the output voltage at a Yn or Z terminal, whichever is assigned as an output.

Symbol	Parameter	Conditions	25	°C	-40 °C to	+125 °C	Unit
			Тур	Max	Max (85 °C)	Max (125 °C)	
t <sub>on</sub>	turn-on time	E to Yn; see Figure 13					
		V <sub>CC</sub> = 2.0 V	80	275	345	415	ns
		V <sub>CC</sub> = 4.5 V	29	55	69	83	ns
		$V_{CC} = 5.0 \text{ V}; C_L = 15 \text{ pF}$	26	-	-	-	ns
		V <sub>CC</sub> = 6.0 V	23	47	59	71	ns
		V <sub>CC</sub> = 9.0 V	17	42	53	63	ns
		Sn to Yn					
		V <sub>CC</sub> = 2.0 V	88	300	375	450	ns
		V <sub>CC</sub> = 4.5 V	32	60	75	90	ns
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF	29	-	-	-	ns
		V <sub>CC</sub> = 6.0 V	26	51	64	77	ns
		V <sub>CC</sub> = 9.0 V	18	45	56	68	ns
		E to Z					
		V <sub>CC</sub> = 2.0 V	85	275	345	415	ns
		V <sub>CC</sub> = 4.5 V	31	55	69	83	ns
		V <sub>CC</sub> = 6.0 V	25	47	59	71	ns
		V <sub>CC</sub> = 9.0 V	18	42	53	63	ns
		Sn to Z					
		V <sub>CC</sub> = 2.0 V	94	300	375	450	ns
		V <sub>CC</sub> = 4.5 V	34	60	75	90	ns
		V <sub>CC</sub> = 6.0 V	27	51	64	77	ns
		V <sub>CC</sub> = 9.0 V	19	45	56	68	ns
C <sub>PD</sub>	power dissipation capacitance	per switch; $V_I = GND$ to $V_{CC}$ [5]	29	-	-	-	pF

- [1]  $t_{pd}$  is the same as  $t_{PHL}$  and  $t_{PLH}$ .
- [2] Due to higher Z terminal capacitance (16 switches versus 1) the delay figures to the Z terminal are higher than those to the Y terminal.
- [3]  $t_{on}$  is the same as  $t_{PHZ}$  and  $t_{PLZ}$ .
- [4]  $t_{off}$  is the same as  $t_{PZH}$  and  $t_{PZL}$ .
- [5]  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu W$ ).

 $P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum \{(C_L + C_{sw}) \times V_{CC}^2 \times f_o\} \text{ where: }$ 

f<sub>i</sub> = input frequency in MHz;

f<sub>o</sub> = output frequency in MHz;

 $\sum \{(C_L + C_{sw}) \times V_{CC}^2 \times f_o\} = sum \text{ of outputs};$ 

 $C_L$  = output load capacitance in pF;

C<sub>sw</sub> = switch capacitance in pF;

 $V_{CC}$  = supply voltage in V.

#### Table 10. Dynamic characteristics 74HCT4067

GND = 0 V;  $t_r = t_f = 6$  ns;  $C_L = 50$  pF unless specified otherwise; for test circuit see Figure 14.

*V<sub>is</sub>* is the input voltage at a Yn or *Z* terminal, whichever is assigned as an input.

 $V_{os}$  is the output voltage at a Yn or Z terminal, whichever is assigned as an output.

Symbol	Parameter	Conditions		25	°C	-40 °C to	+125 °C	Unit
				Тур	Max	Max (85 °C)	Max (125 °C)	
t <sub>pd</sub>	propagation delay	Yn to Z; see Figure 12	[1][2]					
		V <sub>CC</sub> = 4.5 V		9	15	19	22	ns
		Z to Yn						
		V <sub>CC</sub> = 4.5 V		6	12	15	18	ns
t <sub>off</sub>	turn-off time	E to Yn; see Figure 13	[3]					
		V <sub>CC</sub> = 4.5 V		26	55	69	83	ns
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF		26	-	-	-	ns
		Sn to Yn						
		V <sub>CC</sub> = 4.5 V		31	55	69	83	ns
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF		30	-	-	-	ns
		E to Z						
		V <sub>CC</sub> = 4.5 V		30	60	75	90	ns
		Sn to Z						
		V <sub>CC</sub> = 4.5 V		35	60	75	90	ns
t <sub>on</sub>	turn-on time	E to Yn; see Figure 13	<u>[4]</u>					
		V <sub>CC</sub> = 4.5 V		32	60	75	90	ns
		$V_{CC} = 5.0 \text{ V}; C_L = 15 \text{ pF}$		32	-	-	-	ns
		Sn to Yn						
		V <sub>CC</sub> = 4.5 V		35	60	75	90	ns
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF		33	-	-	-	ns
		E to Z						
		V <sub>CC</sub> = 4.5 V		38	65	81	98	ns
		Sn to Z						
		V <sub>CC</sub> = 4.5 V		38	65	81	98	ns
C <sub>PD</sub>	power dissipation capacitance	per switch; $V_I = GND$ to $(V_{CC} - 1.5 V)$	[5]	29	-	-	-	pF

- [1]  $t_{pd}$  is the same as  $t_{PHL}$  and  $t_{PLH}$ .
- [2] Due to higher Z terminal capacitance (16 switches versus 1) the delay figures to the Z terminal are higher than those to the Y terminal.
- [3]  $t_{on}$  is the same as  $t_{PHZ}$  and  $t_{PLZ}$ .
- [4]  $t_{off}$  is the same as  $t_{PZH}$  and  $t_{PZL}$ .
- [5]  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu W$ ).

 $P_D = C_{PD} \times V_{CC}{}^2 \times f_i + \sum \{(C_L + C_{sw}) \times V_{CC}{}^2 \times f_o\}$  where:

 $f_i$  = input frequency in MHz;

 $f_o = output frequency in MHz;$ 

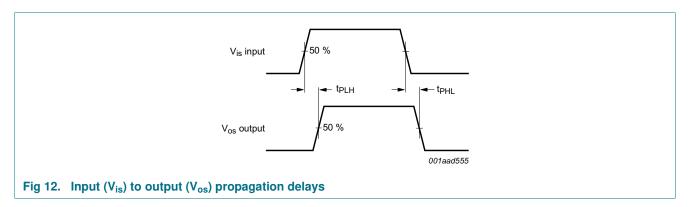
 $\sum \{(C_L + C_{sw}) \times V_{CC}^2 \times f_o\} = sum \ of \ outputs;$ 

 $C_L$  = output load capacitance in pF;

C<sub>sw</sub> = switch capacitance in pF;

 $V_{CC}$  = supply voltage in V.

### 12. Waveforms



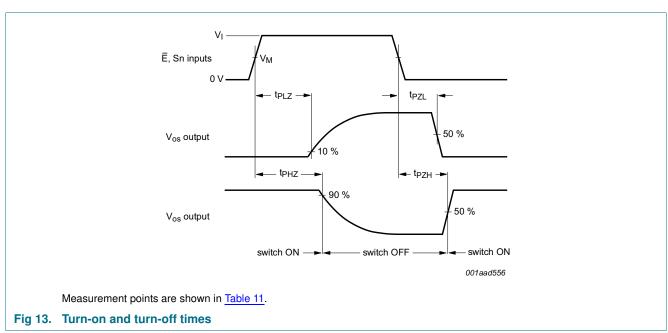
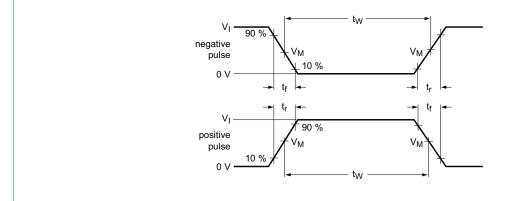
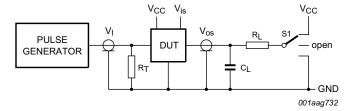


Table 11. Measurement points

Туре	$V_{\mathbf{I}}$	V <sub>M</sub>
74HC4067	V <sub>CC</sub>	0.5V <sub>CC</sub>
74HCT4067	3.0 V	1.3 V





Test data is given in Table 12.

Definitions test circuit:

 $R_T$  = Termination resistance should be equal to output impedance  $Z_0$  of the pulse generator.

 $C_L$  = Load capacitance including jig and probe capacitance.

R<sub>L</sub> = Load resistance.

S1 = Test selection switch.

Fig 14. Test circuit for measuring switching times

Table 12. Test data

Test	Input	Output	S1 position					
	Control E	Address Sn	Switch Yn (Z)	Switch Yn (Z) t <sub>r</sub> , t <sub>f</sub>		Switch Z (Yn)		
	V <sub>I</sub> [1]	V <sub>I</sub> [1]	V <sub>is</sub>	_	C <sub>L</sub>	R <sub>L</sub>	_	
t <sub>PHL</sub> , t <sub>PLH</sub>	GND	GND or V <sub>CC</sub>	GND to V <sub>CC</sub>	6 ns	50 pF	-	open	
t <sub>PHZ</sub> , t <sub>PZH</sub>	GND to V <sub>CC</sub>	GND to V <sub>CC</sub>	V <sub>CC</sub>	6 ns	50 pF, 15 pF	1 kΩ	GND	
$t_{PLZ}, t_{PZL}$	GND to V <sub>CC</sub>	GND to V <sub>CC</sub>	GND	6 ns	50 pF, 15 pF	1 kΩ	$V_{CC}$	

[1] For 74HCT4067: maximum input voltage  $V_I = 3.0 \text{ V}$ .

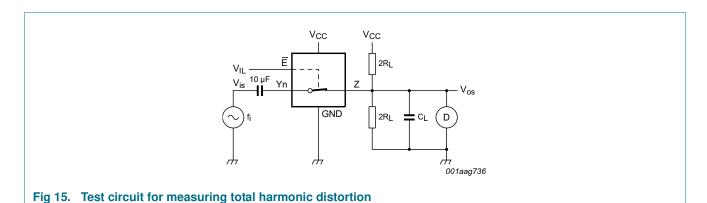
### 13. Additional dynamic characteristics

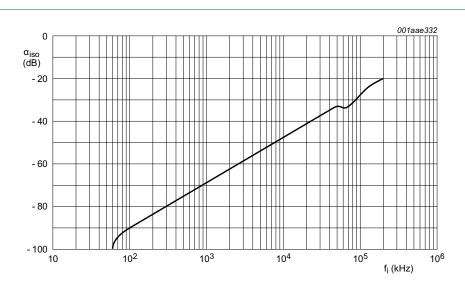
#### Table 13. Additional dynamic characteristics

Recommended conditions and typical values;  $GND = 0 \ V$ ;  $T_{amb} = 25 \ ^{\circ}C$ .  $V_{is}$  is the input voltage at a Yn or Z terminal, whichever is assigned as an input.  $V_{os}$  is the output voltage at a Yn or Z terminal, whichever is assigned as an output.

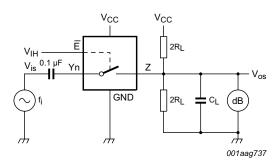
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
THD	total harmonic distortion	$R_L = 10 \text{ k}\Omega$ ; $C_L = 50 \text{ pF}$ ; see Figure 15				
		$f_i = 1 \text{ kHz}$				
		$V_{CC} = 4.5 \text{ V}; V_{is(p-p)} = 4.0 \text{ V}$	-	0.04	-	%
		$V_{CC} = 9.0 \text{ V}; V_{is(p-p)} = 8.0 \text{ V}$	-	0.02	-	%
		$f_i = 10 \text{ kHz}$				
		$V_{CC} = 4.5 \text{ V}; V_{is(p-p)} = 4.0 \text{ V}$	-	0.12	-	%
		$V_{CC} = 9.0 \text{ V}; V_{is(p-p)} = 8.0 \text{ V}$	-	0.06	-	%
$\alpha_{\text{iso}}$	isolation (OFF-state)	$R_L = 600 \Omega$ ; $C_L = 50 pF$ ; see Figure 16				
		V <sub>CC</sub> = 4.5 V	-	-50	-	dB
		V <sub>CC</sub> = 9.0 V	-	-50	-	dB
f <sub>(-3dB)</sub>	-3 dB frequency response	$R_L = 50 \Omega$ ; $C_L = 10 pF$ ; see Figure 17				
		V <sub>CC</sub> = 4.5 V	-	90	-	MHz
		V <sub>CC</sub> = 9.0 V	-	100	-	MHz
C <sub>sw</sub>	switch capacitance	independent pins Y	-	5	-	рF
		common pin Z	-	45	-	рF

- [1] Adjust input voltage  $V_{is}$  to 0 dBm level (0 dBm = 1 mW into 600  $\Omega$ ).
- [2] Adjust input voltage V<sub>is</sub> to 0 dBm level at V<sub>os</sub> for f<sub>i</sub> = 1 MHz (0 dBm = 1 mW into 50 Ω). After set-up, f<sub>i</sub> is increased to obtain a reading of -3 dB at V<sub>os</sub>.





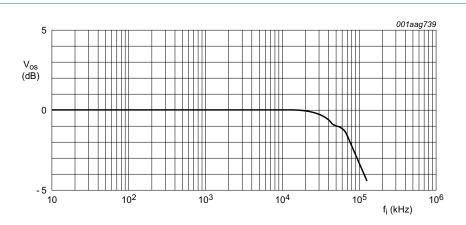
a. Isolation (OFF-state)



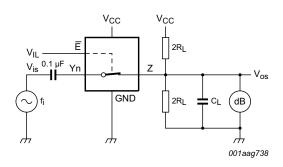
b. Test circuit

 $\mbox{V}_{\mbox{CC}}$  = 4.5 V; GND = 0 V;  $\mbox{R}_{\mbox{L}}$  = 600  $\Omega;$   $\mbox{R}_{\mbox{source}}$  = 1 k $\Omega.$ 

Fig 16. Isolation (OFF-state) as a function of frequency



a. Typical -3 dB frequency response



b. Test circuit

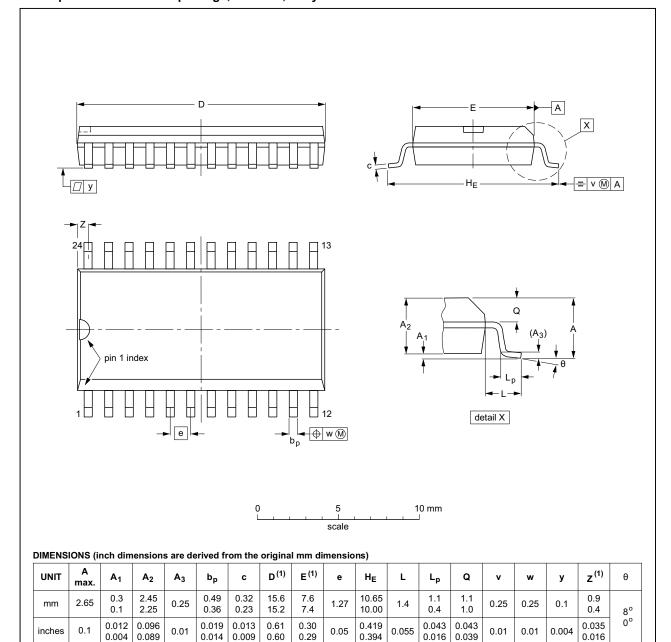
 $\mbox{V}_{\mbox{CC}}$  = 4.5 V; GND = 0 V;  $\mbox{R}_{\mbox{L}}$  = 50  $\Omega;$   $\mbox{R}_{\mbox{source}}$  = 1 k $\Omega.$ 

Fig 17. -3 dB frequency response

### 14. Package outline

#### SO24: plastic small outline package; 24 leads; body width 7.5 mm

SOT137-1



#### Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	JEITA		PROJECTION	1330E DATE
SOT137-1	075E05	MS-013				<del>99-12-27</del> 03-02-19

Fig 18. Package outline SOT137-1 (SO24)

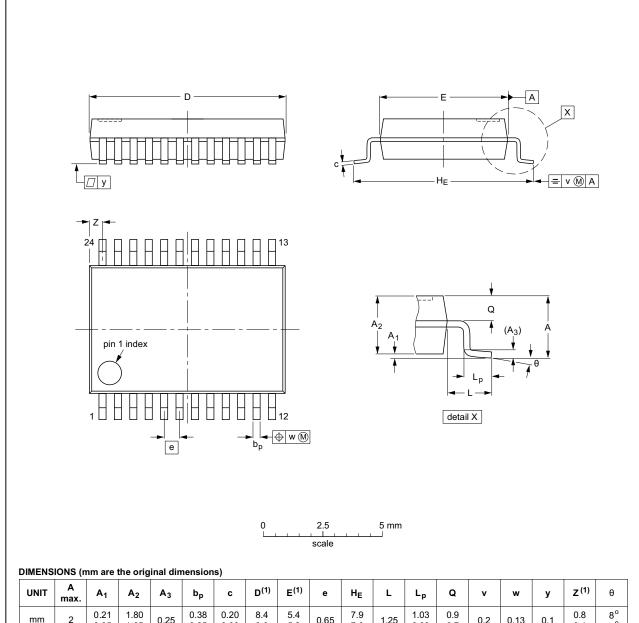
74HC\_HCT4067

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SSOP24: plastic shrink small outline package; 24 leads; body width 5.3 mm

SOT340-1



	(					-,												
UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	bp	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	HE	L	Lp	Q	v	w	у	Z <sup>(1)</sup>	θ
mm	2	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	8.4 8.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.8 0.4	8° 0°

1. Plastic or metal protrusions of 0.2 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE	
SOT340-1		MO-150				<del>99-12-27</del> 03-02-19	

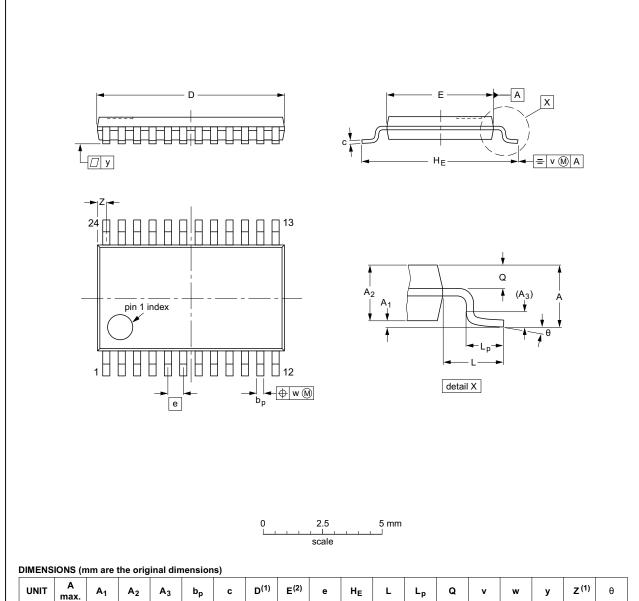
Fig 19. Package outline SOT340-1 (SSOP24)

74HC\_HCT4067

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TSSOP24: plastic thin shrink small outline package; 24 leads; body width 4.4 mm

SOT355-1



				,		-,												
UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	bp	С	D <sup>(1)</sup>	E <sup>(2)</sup>	е	HE	L	Lp	Q	v	w	у	Z (1)	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	7.9 7.7	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

#### Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT355-1		MO-153				<del>-99-12-27</del> 03-02-19

Fig 20. Package outline SOT355-1 (TSSOP24)

74HC\_HCT4067

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DHVQFN24: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 24 terminals; body  $3.5 \times 5.5 \times 0.85$  mm

SOT815-1

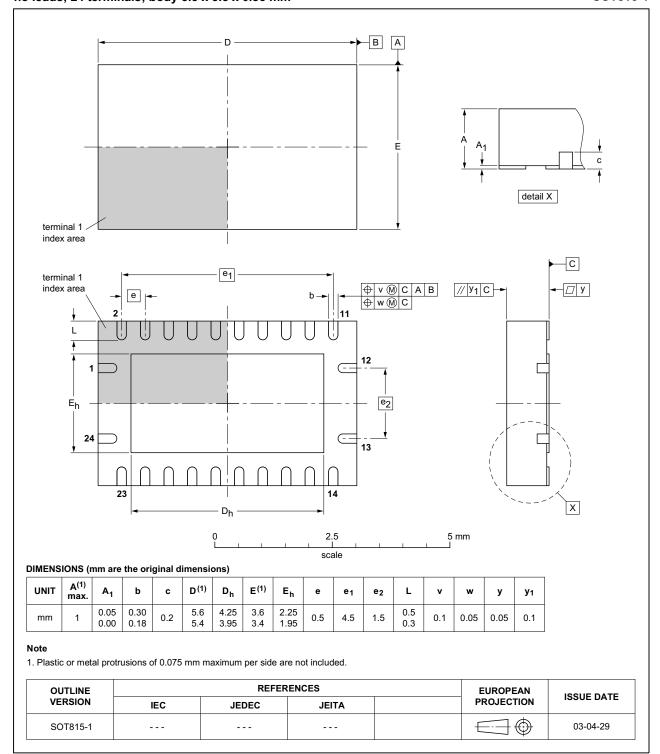


Fig 21. Package outline SOT815-1 (DHVQFN24)

74HC\_HCT4067

### 15. Revision history

#### Table 14. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT4067 v.6	20150522	Product data sheet	-	74HC_HCT4067 v.5
Modifications:	Type numbers	s 74HC4067N and 74HCT4067	7N (SOT101-1) remo	oved.
	• Figure 8, Figu	<u>ire 9</u> : Figure note V <sub>is</sub> = 0 V to (	V <sub>CC</sub> -GND) changed	I to $V_{is} = 0 V$ to $V_{CC}$ .
74HC_HCT4067 v.5	20111213	Product data sheet	-	74HC_HCT4067 v.4
Modifications:	• Legal pages u	ipdated.		
74HC_HCT4067 v.4	20110518	Product data sheet	-	74HC_HCT4067 v.3
74HC_HCT4067 v.3	20071015	Product data sheet	-	74HC_HCT4067_CNV v.2
74HC_HCT4067_CNV v.2	19970901	Product specification	-	-

### 16. Legal information

#### 16.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions"
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <a href="http://www.nxp.com">http://www.nxp.com</a>.

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#### 16-channel analog multiplexer/demultiplexer

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### 18. Contents

1	General description
2	Features and benefits
3	Applications
4	Ordering information
5	Functional diagram 2
6	Pinning information 5
6.1	Pinning
6.2	Pin description 5
7	Functional description 6
8	Limiting values 6
9	Recommended operating conditions 7
10	Static characteristics 8
11	Dynamic characteristics 13
12	Waveforms
13	Additional dynamic characteristics 18
14	Package outline 21
15	Revision history
16	Legal information
16.1	Data sheet status
16.2	Definitions
16.3	Disclaimers
16.4	Trademarks27
17	Contact information 27
18	Contents 28

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